PCN# : P286A
Issue Date : Oct. 11, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jan. 09, 2013

Expected First Date Code of Changed Product :1249

Description of Change (From) :
The products identified in the affected FSID list assembled in Power 56 package at Fairchild Semiconductor in Cebu, Philippines (FSCB).

Description of Change (To) :
The products identified in the affected FSID list assembled in Power 56 package at GEM Shanghai, China. This Power 56 package was previously qualified at GEM Shanghai, China by Fairchild in 2009

BOM comparison between GEM and FSCB as below:

Process/Material	GEM	FSCB
Lead Frame	Bare Cu	Bare Cu
Die Attach Material	Soft Solder	Soft Solder
Wire Bonding Material	Al/Cu/Au/Al ribbon	Al/Cu/Au/Al ribbon
Mold Material	CEL9240HF10	CEL-9240HF10LS

Reason for Change:
To have an alternate assembly and test site to increase manufacturing capacity.

Affected Product(s):

FDMS0300S	FDMS0302S	FDMS0306S
FDMS3662	FDMS6673BZ	FDMS6681Z
FDMS7656AS	FDMS7658AS	FDMS7660
FDMS7660AS	FDMS7670	FDMS7670AS
FDMS7672AS	FDMS8018	FDMS8023S
FDMS8025S	FDMS8460	FDMS86101
FDMS86101_SN00155	FDMS86200	FDMS86300
FDMS86322	FDMS86500L	FDMS86540

Qualification Plan	Device	Package	Process	No. of Lots
QP12130986	FDMS8460	PQFN5X6	DMOS	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/154
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/77
Highly Accelerated Stress Test	130C, 85%RH, 5.0V	JESD22-A110	96 hrs	0/77

Qualification Plan	Device	Package	Process	No. of Lots
QP12130986	FDMS3662	PQFN5X6	PT3	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/154
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/77
Highly Accelerated Stress Test	130C, 85%RH, 5.0V	JESD22-A110	96 hrs	0/77

Qualification Plan	Device	Package	Process	No. of Lots
QP12130986	FDMS6673BZ	PQFN5X6	ST3	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/154
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/77
Highly Accelerated Stress Test	130C, 85%RH, 5.0V	JESD22-A110	96 hrs	0/77

Qualification Plan	Device	Package	Process	No. of Lots
QP12130986	FDMS0308S	PQFN5X6	ST7	1

Test Description:	Condition:	Standard :	Duration:	Results:
MSL1 Precondition	260C, 3 cycles	JESD22-A113		0/154
Temperature Cycle	-65C, 150C	JESD22-A104	500 cycles	0/77
Highly Accelerated Stress Test	130C, 85%RH, 5.0V	JESD22-A110	96 hrs	0/77